



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-03-29
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST5P3LLH6	C107*6B31B6F	A	998G	2018-03-29
Amount	UoM	Unit type	ST ECOPACK Grade	
80	mg	Each	ECOPACK2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	4.9-6-1.75	8	GULL WING	
Comment	SO 08 .15 JEDEC			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017	
Query	Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	TRUE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	FALSE

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	C107*6B3186F					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	0.586	mg	supplier	die	Silicon (Si)	7440-21-3		0.562	mg	959044	7025
				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	25597	188
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	6827	50
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	8532	63
Leadframe	M-004 Copper and its alloys	30.268	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.709	mg	981532	371363
				supplier	alloy	Iron (Fe)	7439-89-6		0.030	mg	991	371
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	297	113
				supplier	metallization	Silver (Ag)	7440-22-4		0.520	mg	17180	6500
Die attach		0.280	mg	supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		0.280	mg	1000000	3500
Bonding wires	M-004 Copper and its alloys	0.163	mg	supplier	wire	Copper (Cu)	7440-50-8		0.163	mg	1000000	2038
Encapsulation	M-011 Other inorganic materials	47.674	mg	supplier	mold compound	Silica, vitreous	60676-86-0		41.285	mg	865986	516063
				supplier	mold compound	Epoxy Resin	25068-38-6		3.576	mg	75010	44700
				supplier	mold compound	Phenol Resin	29690-82-2		2.384	mg	50006	29800
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.191	mg	4006	2388
				supplier	mold compound	Carbon black	1333-86-4		0.238	mg	4992	2975
connections coating	Solder	1.029	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.029	mg	1000000	12863